IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information						
Supplie	r Information														
Company name* Compa				ompany unique ID			Unique ID Authority					Response Date*			
onsemi												2023-06-08			
Contact N	lame	Title - Contact				Phone - Contact*				Email - Contact*					
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name			·	Effective Da	Date Version Manufacturing Site		uring Site	V	Veight*	UOM	Unit Type	
		FSGM04	65RWDTU	Green Mode FPS			2023-06-08			РВВ		2	239.009	mg	Each
Manufa	cturing Process Informati	ion													
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-0		-STD-020 MS	L Rating	Peak Process Body Temperat		ture Max Time at Peak Temper		Temperatu	re Numb	per of Reflow Cyc	les	
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0	0 C		30 seco		second	ls 3			
Comments	S														
or more	information regarding material c	composition j	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.8	mg	Supplier	Silicon (Si)	7440-21-3		9.8	mg
Die Attach Epoxy	0.254	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0076	mg
			Supplier	Miscellaneous	Trade Secret		0.0127	mg
			Supplier	Silver (Ag)	7440-22-4		0.2159	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0178	mg
Die Attach Solder	3.061	mg	Supplier	Silver (Ag)	7440-22-4		0.0765	mg
			A	Lead (Pb)	7439-92-1	7a	2.8314	mg
			Supplier	Tin (Sn)	7440-31-5		0.1531	mg
Lead Frame	1264.59	mg	Supplier	Silver (Ag)	7440-22-4		2.91	mg
			Supplier	Tin (Sn)	7440-31-5		1.55	mg
			Supplier	Copper (Cu)	7440-50-8		1260.0045	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1255	mg
Mold Compound-Black	950.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		114	mg
			Supplier	Carbon Black (C)	1333-86-4		4.75	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		831.25	mg
Plating	11.0	mg	Supplier	Tin (Sn)	7440-31-5		11	mg
Wire Bond - Cu	0.304	mg	Supplier	Copper (Cu)	7440-50-8		0.304	mg